

Table of Contents

OverView 1

Specifications 1

OverView 1

OverView

Specifications

Model	IIM-3000
Target Wafer	Φ 300 mm Si Wafer (Polished, Etched) / N, P-, P+, P++
Detectable Defects	Buried-Airpocket, Surface Bump, Through-Hole
Min. Detectable Airpocket	APK $\geq 20 \mu\text{m}$ diameter Capture Rate (DSP): $\geq 95 \%$ for $25 \mu\text{m}$ APK Capture Rate (Ground): $\geq 95 \%$ for $30 \mu\text{m}$ APK
Defect Information	Diameter, Long-Short Ratio, Circularity X,Y,Z coordinate (Z means the depth of defect)
Throughput	120 Wfrs/h
Dimension	1450 mm (W) x 2300 mm (D) x 2010 mm (H)
Weight	1300 Kg

OverView

- IIM-3000 is a equipment that detects all defects and measures the size of each defect on 300 mm Si wafers. Followings are the types of defects that IIM-3000 can detect ; Buried airpockets, Bumps and Through-holes.
- The advanced defect detection and classification algorithms, enable users to detect easily all defects in various Si wafers(N. P-, P +, P ++) with high throughput.
- A specialized controller for IIM-3000 provides the optimized control unit, which enables easy maintenance and quick setup.

- By applying optimized software, IIM-3000 provides reliable inspection quality and result data for users also.

From:

<http://comizoa.co.kr/info/> - -

Permanent link:

http://comizoa.co.kr/info/doku.php?id=en:equipment:iim3000:20_overview&rev=1587708033

Last update: **2024/07/08 18:22**